

Product Information Sheet

EPO-TEK® E3037

Date: September 2017 Recommended Cure: 150°C / 1 Hour

Rev: III

No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 3.07
Pot Life: 28 Days

Shelf Life- Bulk: One year at -40°C

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

<u>Product Description:</u> A single component, electrically conductive, thixotropic silver-filled epoxy for die-attach and SMD-attach inside hybrid microelectronics.

<u>Typical Properties:</u> Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:					
* Color (before cure):		Silver			
* Consistency:		Smooth flowin	g paste		
* Viscosity (23°C) @ 10 rpm:		22,000-	26,000	cPs	
Thixotropic Index:			3.6		
* Glass Transition Temp:		≥ 90		°C (Dyn	namic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansi	on (CTE):				
•	Below Tg:		52		n/in°C
	Above Tg:		148	x 10 ⁻⁶ i	n/in°C
Shore D Hardness:			80		
Lap Shear @ 23°C:			1,880	psi	
Die Shear @ 23°C:			≥ 10	Kg :	3,556 psi
Degradation Temp:			358	°C	
Weight Loss:					
	@ 200°C:		0.13	%	
	@ 250°C:		0.41	%	
	@ 300°C:		0.80	%	
Suggested Operating Temperature:		< 300		°C (Intermittent)	
Storage Modulus:			27,680	psi	
Ion Content:			37 ppm	Na⁺:	22 ppm
		NH ₄ +: 6	35 ppm	K+:	3 ppm
* Particle Size:			≤ 20	micron	ns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.6	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0005	Ohm-cm